

Handling Switches

Introduction

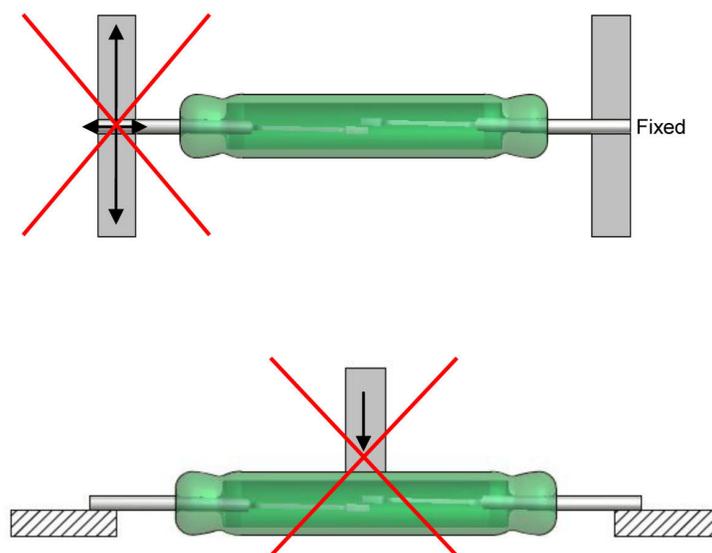
A dry-reed switch can be defined as an assembly that contains two ferromagnetic NiFe contact blades, hermetically sealed in a glass envelope and filled with an inert gas. The inert gas atmosphere protects the contact resistance of the reed switch, which is one of its most important electrical performance characteristics. The inert atmosphere is maintained by the integrity of the critical glass-to-metal seal of the switch. This seal is defined as a “residual stress seal,” which means that the seal is sensitive to handling. When properly made, this seal will maintain the inert gas atmosphere of the reed switch for a maximum of thirty (30) years. However, improper handling of the switch and the application of the excessive mechanical force of the switch leads (for example) during assembly on prints may result in a loss of the seal hermeticity. If damage is caused, it might be immediately visible as a glass crack in the seal area with or without the evidence of chipped glass particles. Or a latent defect may be created that will deteriorate the seal hermeticity over time due to the residual stress of the seal being altered through the improper application of a mechanical force. Once the seal integrity is compromised, atmosphere oxygen and other contaminants will degrade the contact resistance and the life expectancy of the switch will be severely impacted.

Switch Lead Handling Recommendations

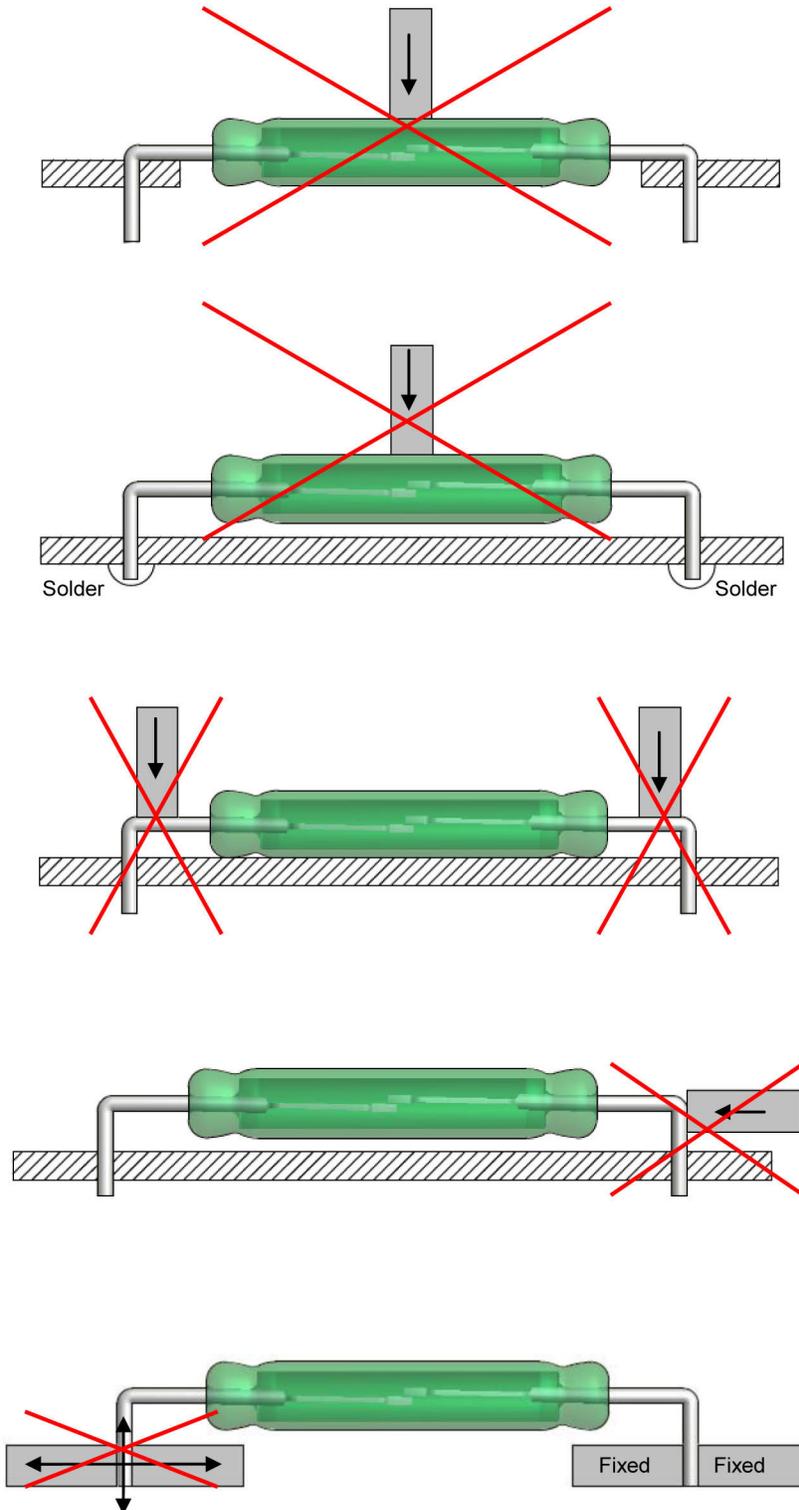
The glass seal has a very high resistance to pressure, but a low resistance to pull forces. The ability of the seal to properly withstand a switch lead handling is dependent on several factors: the relation of the wire-to-glass dimensions, the length of the seal, the pull force or type of handling to be performed, and the distance and direction of the mechanical force in relation to the seal itself.

Therefore, the proper support and clamping of the leads is necessary to avoid damage to the seal. Even then, the plastic deformation strain of the NiFe lead wires can be transmitted through the clamping area and into the seal. Depending on the combination of the force and the distance of the clamping area to the seal, damage may still result.

In the following figures, handling examples are given that are unacceptable.

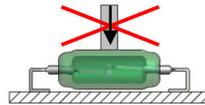
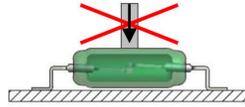


Handling Switches

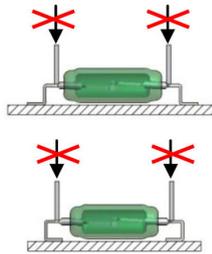


Handling Switches

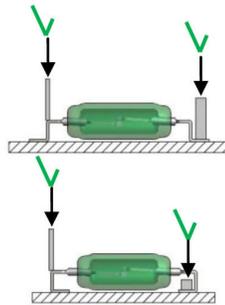
The handling of SMD switches are similar to the normal switches, but some bent SMD types need to be handled different as the examples shown below.



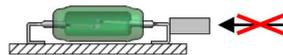
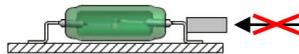
Don't ad pressure on the glass on placing the SMD switch on a pcb.
This can result into glass cracks.



Don't ad pressure on the leads, directly beside the glass-metal connection.
This can result into glass cracks.



Pressure can be applied directly on the horizontal bent SMD-pad
or straight on the vertical bent SMD-pad.



After soldering, don't apply pressure on the SMD-switch, for instance sideways.
This could result in bent SMD-pads, bent wire and glass cracks.